# MA2SD30

### Silicon epitaxial planar type

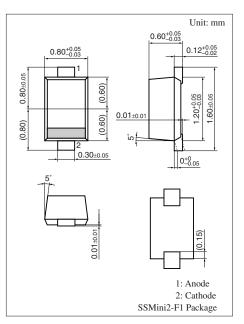
For super high speed switching

#### Features

- Small reverse current:  $I_R < 2 \ \mu A$  (at  $V_R = 30 \ V$ )
- Optimum for high frequency rectification because of its short reverse recovery time t<sub>rr</sub>.

Absolute Maximum Ratings $T_a = 25$ C						
Parameter	Symbol	Rating	Unit			
Reverse voltage	V <sub>R</sub>	30	V			
Repetitive peak reverse voltage	V <sub>RRM</sub>	30	V			
Forward current (Average)	I <sub>F(AV)</sub>	100	mA			
Peak forward current	$I_{FM}$	200	mA			
Non-repetitive peak forward	I <sub>FSM</sub>	1	А			
surge current *						
Junction temperature	$T_j$	125	°C			
Storage temperature	T <sub>stg</sub>	-55 to +125	°C			

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$



Marking Symbol: 8N

Note) \*: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

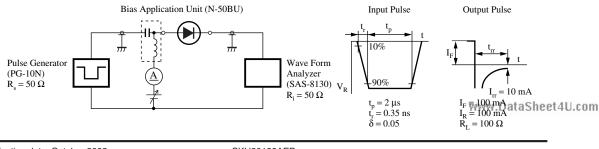
#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse current	I <sub>R1</sub>	$V_R = 10 V$			0.3	μΑ
	I <sub>R2</sub>	$V_R = 30 V$			2	
Forward voltage	V <sub>F1</sub>	$I_F = 10 \text{ mA}$		0.38	0.44	V
	V <sub>F2</sub>	$I_F = 100 \text{ mA}$		0.51	0.58	
Terminal capacitance	Ct	$V_R = 0 V, f = 1 MHz$		9		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 100 \text{ mA}$		1		ns
		$I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$				

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

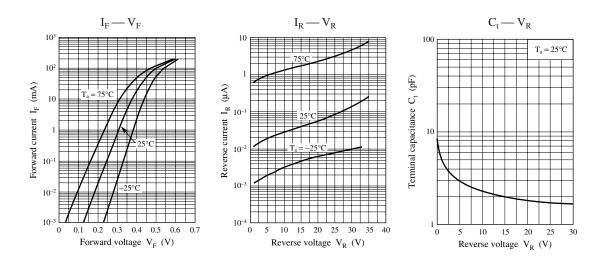
- 3. Absolute frequency of input and output is 250 MHz
- 4. \*: t<sub>rr</sub> measurement circuit



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2

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